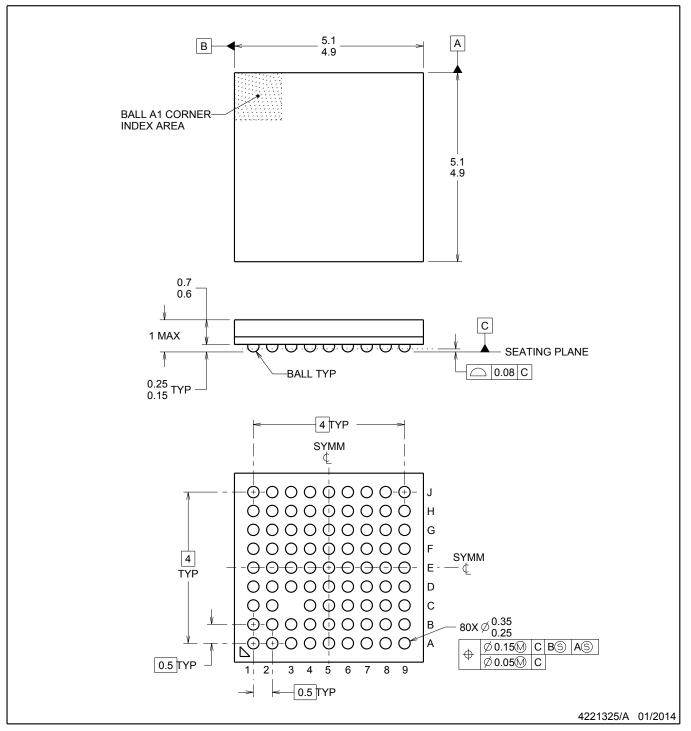
ZXH0080A



PACKAGE OUTLINE

NFBGA - 1 mm max height

BALL GRID ARRAY



NOTES:

- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis is for reference only. Dimensioning and tolerancing per ASME Y14.5M.
- 2. This drawing is subject to change without notice.
- 3. This is a Pb-free solder ball design.

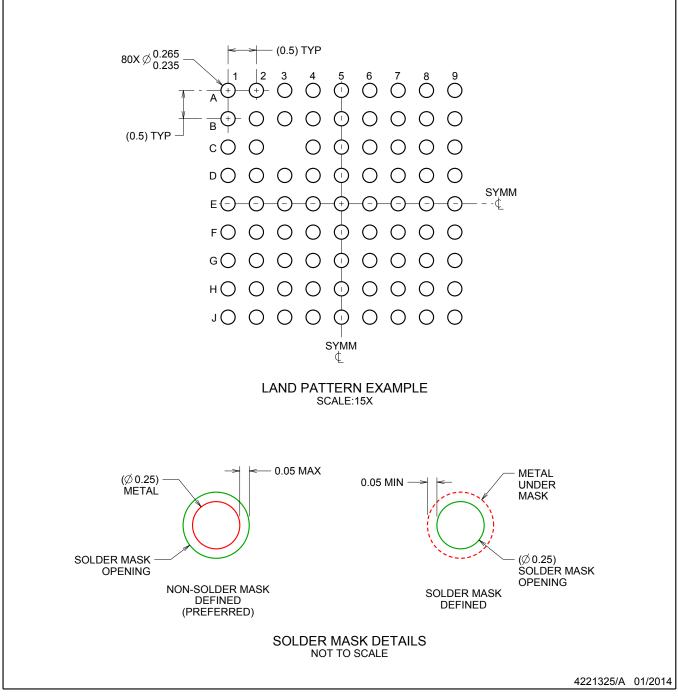


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EXAMPLE BOARD LAYOUT

NFBGA - 1 mm max height

BALL GRID ARRAY



NOTES: (continued)

3. Final dimensions may vary due to manufacturing tolerance considerations and also routing constraints. See Texas Instruments Literature No. SBVA017 (www.ti.com/lit/sbva017).

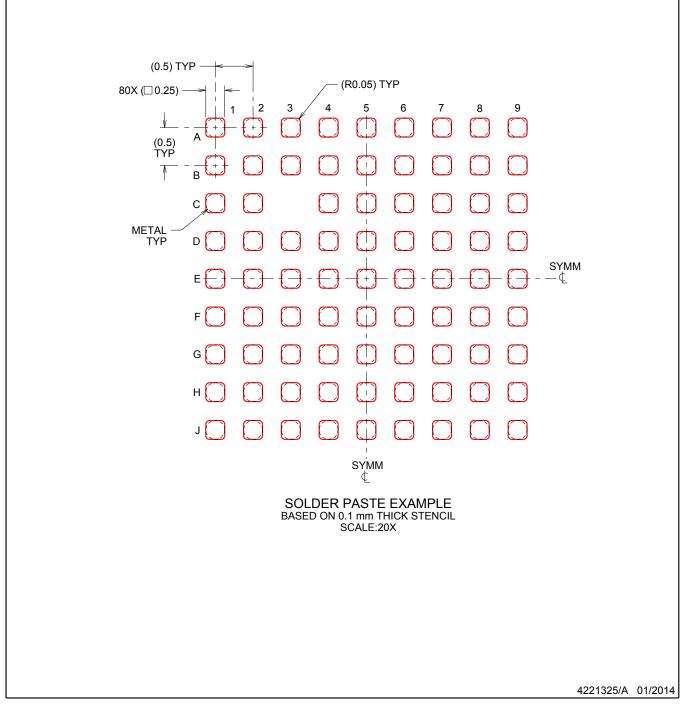


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EXAMPLE STENCIL DESIGN

NFBGA - 1 mm max height

BALL GRID ARRAY



NOTES: (continued)

4. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release.



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